

ELECTRICS & ELECTRONICS | SEMICOSIL® 962 TC

THERMALLY CONDUCTIVE GAP FILLER WITH 3 W/mK

SEMICOSIL® 962 TC

WACKER expands its thermal conductive material portfolio by a new gap filler for electronics and electrical applications as well as for battery applications. The constantly increasing demand for heat dissipation between two substrates with high tolerances calls for a gap filler, which is easy and cost effectively to handle and renders save functionality and durability.

Product Description

SEMICOSIL® 962 TC is a shear-thinning, easy dispensing, non-slump, addition-curing, two part silicone rubber that cures at room temperature to a soft, flexible and tacky rubber with excellent thermal conductivity.

Features of SEMICOSIL® 962 TC

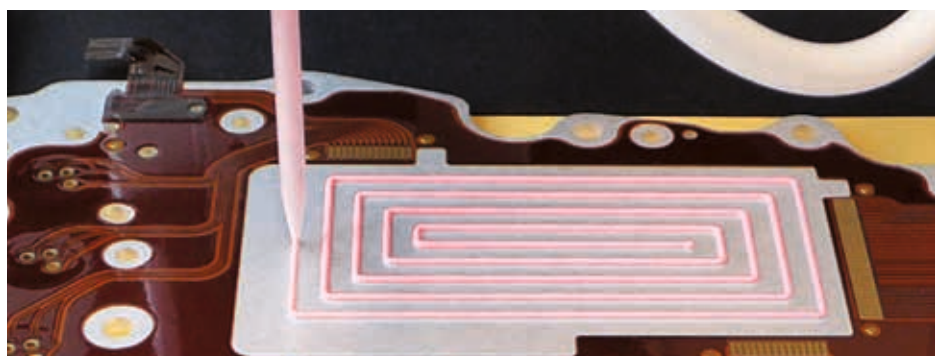
- Gap filler, thermal conductivity 3 W/mK
- Two-part, RT curing
- Constant properties from -50 °C to +180 °C
- Low stress, soft and tacky
- Low volatile D4-D8 <350 ppm
- Low abrasiveness

Applications

- Automotive electronics
- Interface material for heat sink applications for the electronics industry
- Heat sink of EH/HEV batteries

Product Information				
Property	Test Method	Unit	A	Value B
Product Data Uncured				
Color			Red	White
Viscosity at 23 °C, cone-plate-viscosimeter	ISO 3219, D = 10 1/s	[mPa s]	150,000	150,000
Density at 23 °C		[g/cm ³]	3.1	3.1
Product Data (Catalyzed A+B)				
Mixing ratio (parts by weight)		A : B		1 : 1
Viscosity of mix, at 23 °C	ISO 3219, D = 10 1/s	[mPa s]		150,000
Pot life (up to 1,000 000 mPa s), at 23 °C		[min]		60
Platinum-catalyst in component				A
Product Data Cured				
Color				Red
Density at 23 °C, in water	DIN 53 479 A / ISO 2781	[g/cm ³]		3.1
Hardness Shore 00	DIN 53 505 / ISO 868			50
Thermal conductivity	ASTM D5470-12	[W/mK]		3.0
Content siloxane D4-D8	NSCG012	[ppm]		< 350
Heat capacity at 30 °C		[J/gK]		1.0
Flame rating, vertical test	Internal test acc. UL94			V-0
Maximum particle size		[micron]		90
Volume resistivity	IEC 93	[Ohm.cm]		>10 ¹³
Dielectric strength	IEC 93	[kV/mm]		7
Cured for 10 min at 165 °C				

These figures are only intended as a guide and should not be used in preparing specifications.





Processing

The platinum catalyst is contained in component A. Only components A and B with the same lot number may be processed together.

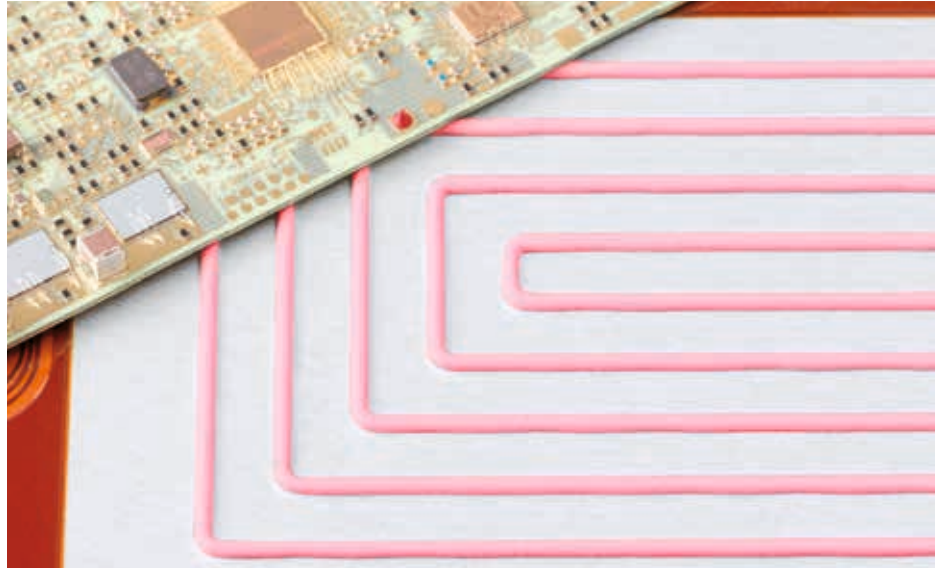
Curing Properties

Temperature	Curing time, thickness 6 mm, 90% cure
25 °C	300 min
100 °C	10 min

Packaging Options

Drum	280 kg / 90 l
Pail, Hobcock	30 kg / 10.7 l
EURO cartridge	930 gr / 300 cc
2-Part cartridge	652 gr
SEMCO® on request*	20 Oz, 6 Oz

* For sampling



SEMICOSIL®

Wacker Chemie AG, 81737 München, Germany, Tel. +49 89 6279-1741, Fax +49 89 6279-1770
 info@wacker.com, www.wacker.com, www.wacker.com/socialmedia



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